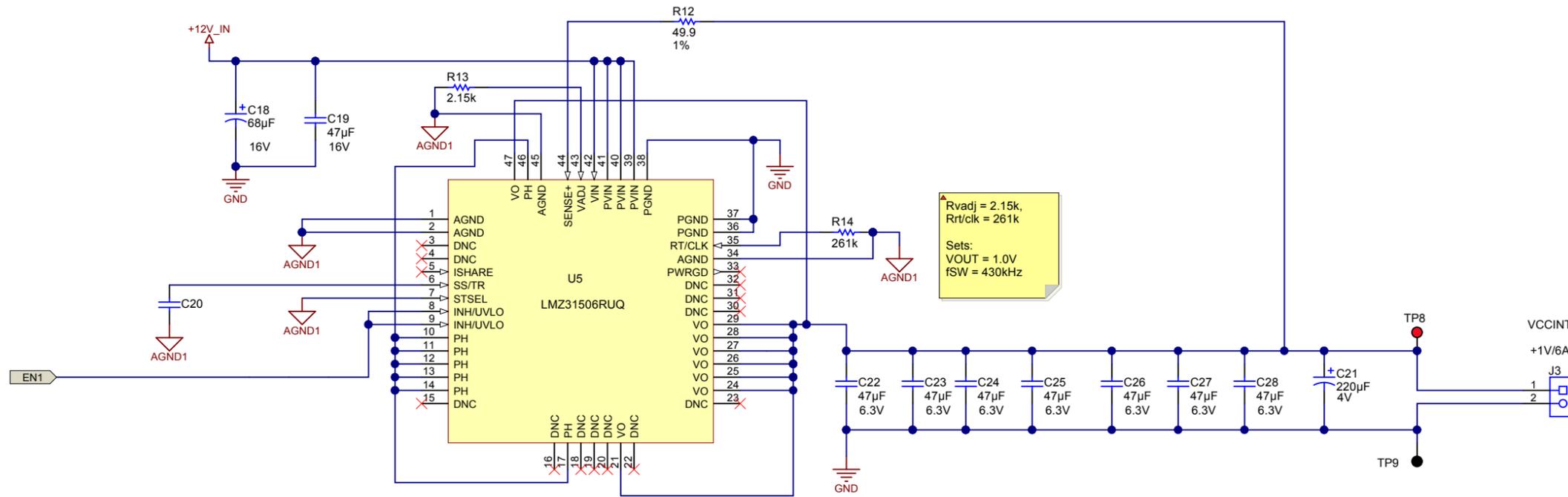
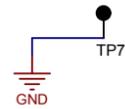
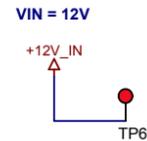
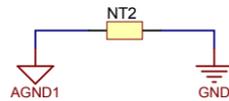


VCCINT, VCCBRAM, MGTAVCC, VCCPINT

1.0V @ 6A



- ⓘ PH pins should be connected to a copper island under the device for thermal relief. DO NOT connect any external component or net to this pin.
- ⓘ DO NOT connect AGNDs on this page to a common system AGND



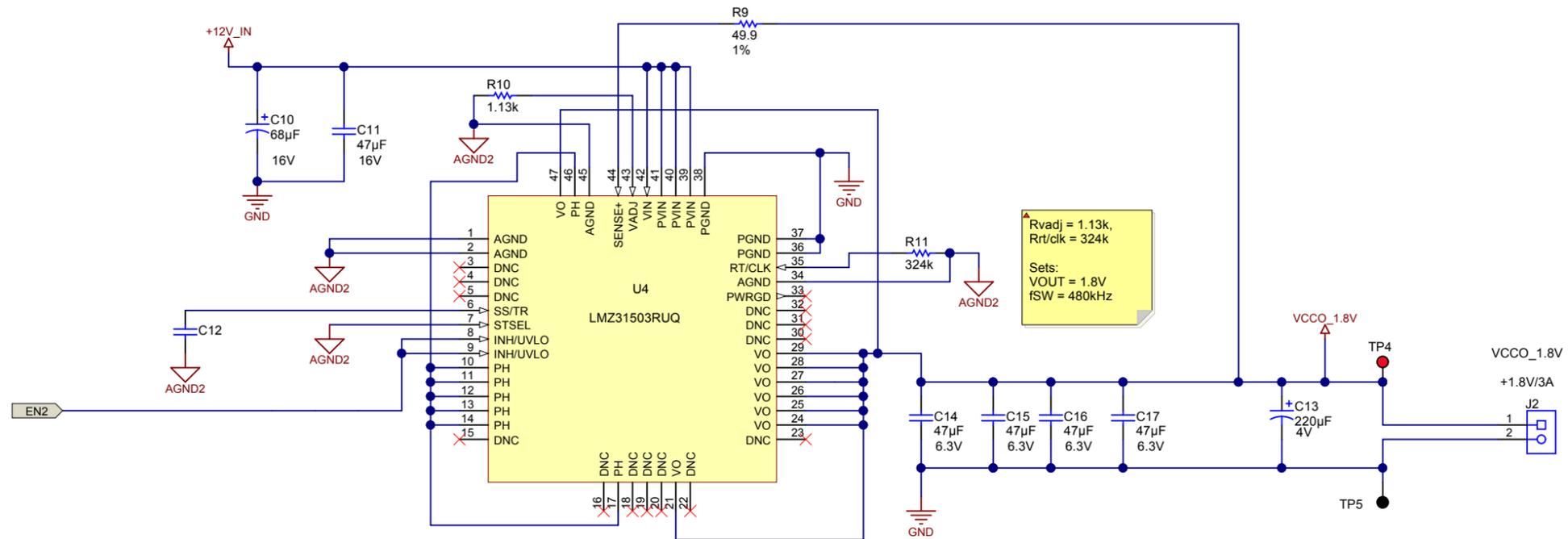
AGND to PGND Strap at ONLY 1 point

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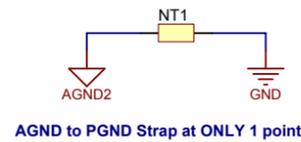
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SVN Rev: Not in version control	Assembly Variant: [No Variations]	Project Title: Xilinx Zynq 8w power reference design	Sheet Title:
Drawn By:	File: VCCINT_SchDoc	Sheet: 1 of 4	Size: B
Engineer: Frank Xiao	Contact: http://www.ti.com/support	TEXAS INSTRUMENTS http://www.ti.com ?Texas Instruments 2015	

VCCAUX, VCCO_1.8V, VCCPAUX, VCCPLL, VCCADC

1.8V @ 3A



- ❗ PH pins should be connected to a copper island under the device for thermal relief. DO NOT connect any external component or net to this pin.
- ❗ DO NOT connect AGNDs on this page to a common system AGND

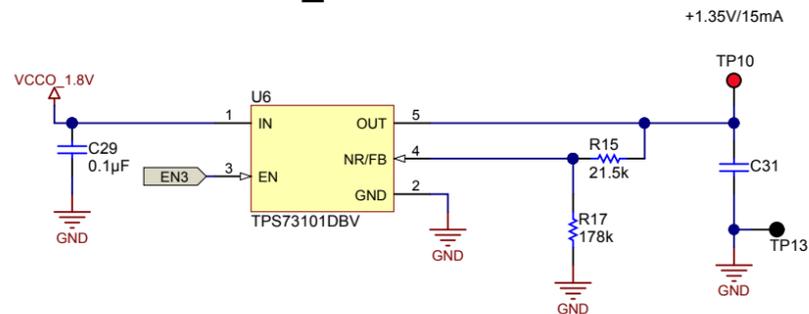


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SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 2 of 4
Drawn By:	File: VCCAUX.SchDoc	Size: B
Engineer: Frank Xiao	Contact: http://www.ti.com/support	http://www.ti.com

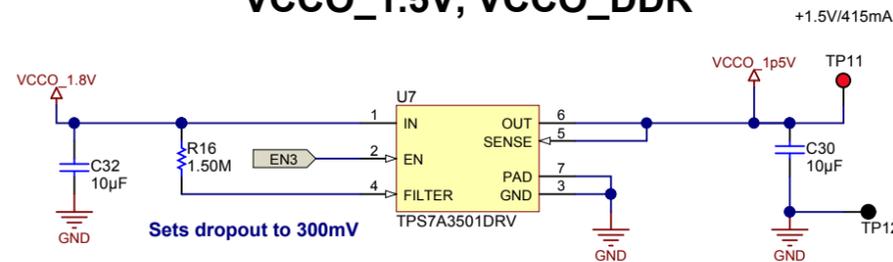
?Texas Instruments 2015

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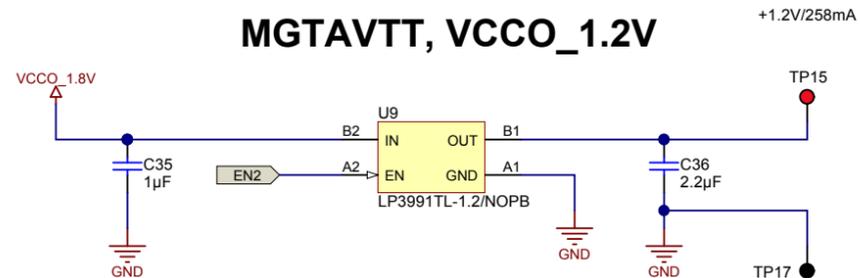
VCC_1.35V



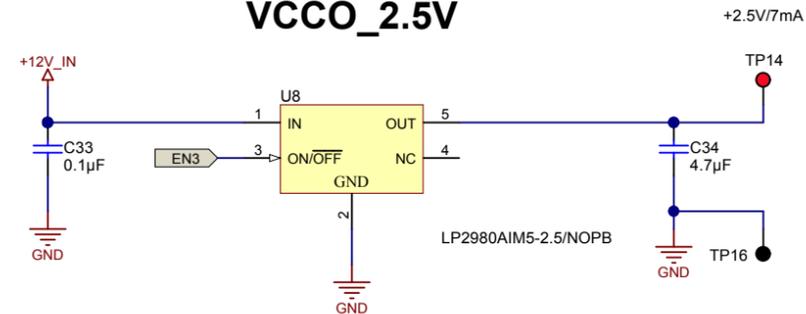
VCCO_1.5V, VCCO_DDR



MGTAVTT, VCCO_1.2V



VCCO_2.5V

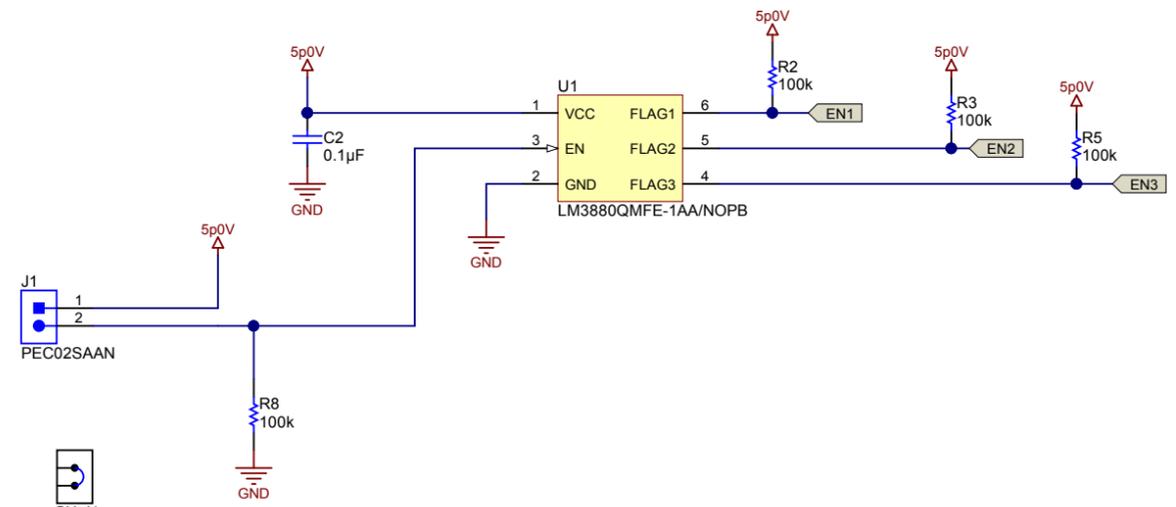


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Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 1/13/2015
TID #: TID	Project Title: Xilinx Zynq 8w power reference design	
Number: PMP10601	Rev: E1	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 3 of 4
Drawn By:	File: VCCO_xx.SchDoc	Size: B
Engineer: Frank Xiao	Contact: http://www.ti.com/support	

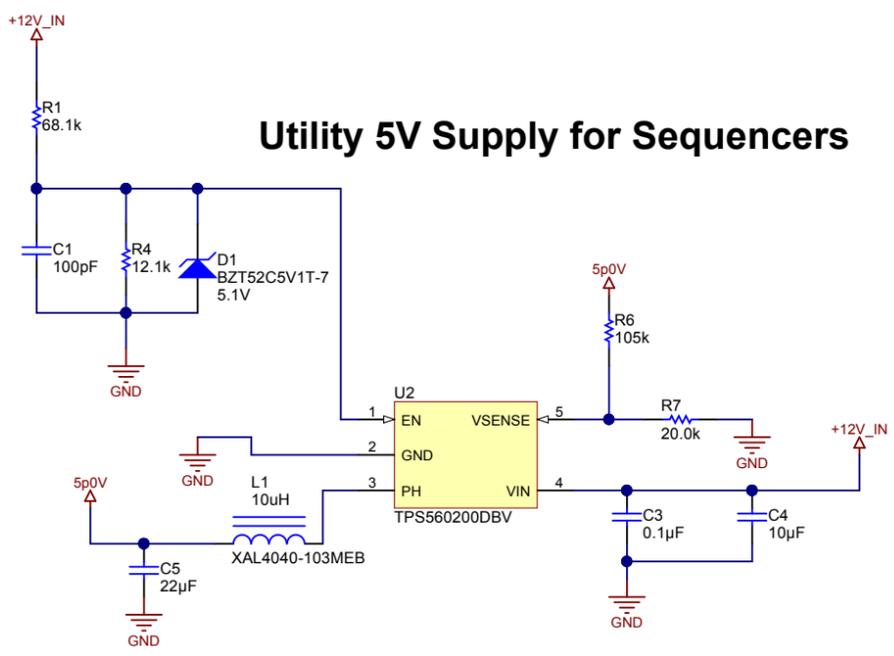


Sequencer

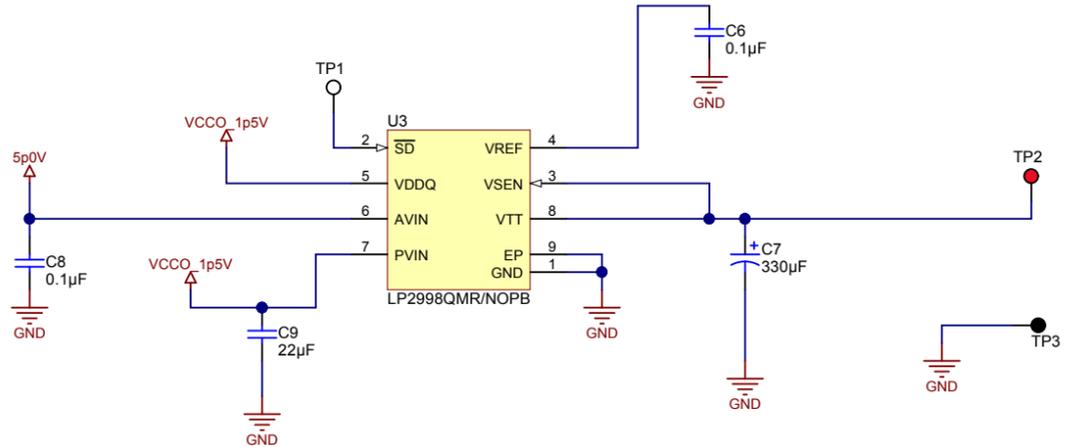


SH-J1 Options:
 Installed - Sequencer Enabled
 Open - Sequencer Disabled

Utility 5V Supply for Sequencers



DDR Termination



Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 1/13/2015
TID #: TID	Project Title: Xilinx Zynq 8w power reference design	
Number: PMP10601	Rev: E1	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 4 of 4
Drawn By:	File: Sequencer.SchDoc	Size: B
Engineer: Frank Xiao	Contact: http://www.ti.com/support	

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